



MP15-35 Material Safety Data Sheet

Material Content Declaration					
Material name	Substance name e.g. Copper (Cu).	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
Terminal 28.01%	Copper (Cu)	7440-50-8	4,187.650	99.979	280,953.2
	Phosphorus (P)	7723-14-0	0.042	0.0010	2.8
	Arsenic (As)	7440-38-2	0.042	0.0010	2.8
	Tin (Sn)	7440-31-5	0.042	0.0010	2.8
	Oxygen (O)	7782-44-7	0.021	0.0005	1.4
	Sulfur (S)	7704-34-9	0.502	0.0120	33.7
	Iron (Fe)	7439-89-6	0.028	0.0007	1.9
	Nickel (Ni)	7440-02-0	0.013	0.0003	0.9
	Bismuth (Bi)	7440-69-9	0.083	0.0020	5.6
	Antimony (Sb)	1309-64-4	0.083	0.0020	5.6
	Lead (Pb)	7439-92-1	0.021	0.0005	1.4
	Zinc (Zn)	7440-66-6	0.013	0.0003	0.9
		Total		4,188.54	
Solder Wafer 0.33%	Lead (Pb)	7439-92-1	44.99	92.50	3,018.4
	Tin (Sn)	7440-31-5	2.43	5.00	163.0
	Silver (Ag)	7440-22-4	1.22	2.51	81.9
		Total		48.64	
Chip 0.25%	Silicon (Si)	7440-21-3	36.09	95.40	2,421.3
	Lead (Pb)	7439-92-1	1.74	4.60	116.8
		Total		37.83	
Case 49.56` %	Epoxy	38891-59-7	3,185.50	43.13	213,718.1
	Aluminium (Al)	7429-90-5	4,201.00	56.87	281,848.9
		Total		7,386.50	
Potting 21.69%	Epoxy	38891-59-7	3,233.00	100.00	216,904.9
		Total		3,233.00	
Plating 0.16%	Nickel (Ni)	7440-02-0	10.64	100.00	713.8
		Total		10.64	
	Total mass (mg)		14,905.15		